



Date: January 30, 2025

RE: Tempe (Fab 2) Wafer Fabrication Facility ISO/IATF Decertification

IATF Certificate: 08435-2002-AQ-HOU-IATF-33RSTM

On December 2, 2024, Microchip announced manufacturing restructuring plans that include the closure of the Tempe (Fab 2) Wafer Fabrication Facility.

This memo is to further announce that as part of the facility closure, its active IATF-16949 certificate will be withdrawn, in early Q3, 2025. Additionally, the facility will be removed from Microchip's Corporate ISO-9001 certificate by the end of 2025.

Microchip is committed to ensuring product quality during the entire time that Fab 2 remains operational. All established and certified process control measures remain in place and adherence to these practices will continue for the life of the fab, regardless of the status of IATF-16949 certification. Additionally, all Microchip devices are 100% electrically tested, with only known good products shipped to customers.

Please contact your local [Microchip Sales Office](#) with questions or concerns regarding this notification.

Regards,
Microchip Corporate Quality Systems

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